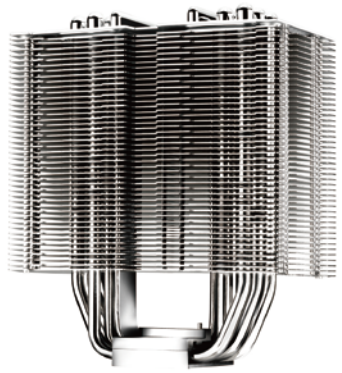
TPC 800

RR-T800-FLNN-R1



TPC 800 is the Cooler Master Reference Cooler for optimal Performance and is a high end cooling system with perfect performance for overclocking. TPC 800 is the first-ever CPU heatsink to use vertical vapor chamber technology and combine it with heatpipe technology: the synergy of both technologies working in tandem delivers the top cooling performance.

Features

- The TPC 800 uses 2 separate cooling technologies to transfer heat – heat pipes and vertical vapor chambers.
- The first-ever CPU heatsink to use vertical vapor chamber technology.
- 100% pure polished copper base – combined with improved soldering technologies for the best thermal transfer.
- Special fin design – heatsink receives concentrated cold airflow.
- Improved air pressure design and fan mounting system.

Specifications

CPU Socket	Intel® LGA 2011/1366/1156/1155/775 AMD FM1/AM3+/AM3/AM2+/AM2
Dimensions	134 x 74 x 158 mm (5.3 x 2.9 x 6.2 in)
Heat Sink Material	Copper Base / 2 Vapor Chambers 6 Heatpipes / Aluminum Fins
Heat Sink Weight	826g (1.83 lb)
Heat Pipe Dimensions	Ø6mm

Warranty

2 years

Package Information

EAN Code	4719512037706
UPC Code	884102017209
Package Dimensions	182 x 118 x 192 mm (7.17 x 4.65 x 7.56 in)
Carton Dimensions	485 x 377 x 216 mm (19.09 x 14.84 x 8.50 in)
Unit / Carton	8
Carton / Pallet	48

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Appendix

Photo taken: Mar. 20, 2012

Synergy cooling: Vapor chamber + Heatpipe	Vertical vapor chamber
Pure polished copper base	Special fin design

Note: Photos may differ slightly from the final product.

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